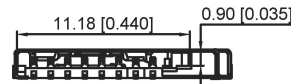


PCB LAYOUT

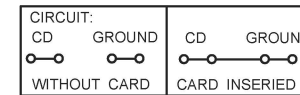
NOTES:

1. MATERIAL:
 - 1.1 Housing:HI-TEMP.PLASIC UL94V-0; Color Black.
 - 1.2 Terminal:Copper Alloy.
 - 1.3 Shell:SUS.
- 2.PLATING:
 - 2.1 Contact: Contact Area:Au G/F, Solder area:Matte tin
 - 2.2 SHELL: Solder Area:Au G/F,Under plate Ni all over
 - 2.3 CD PIN: Contact Area:Au G/F,Under plate all over
3. SPECIALITY:
 - 3.1 Rated current:1.0A
 - 3.2 Rated voltage:30V
 - 3.3 Contact Resistance:50mΩ MAX
 - 3.4 Insulation Resistance:1000MΩ MIN 500V DC
 - 3.5 Dielectric withstanding voltage: 500V AC.
 - 3.6 Solderability:25±5°C, 5±0.5s.
 - 3.7 Durability:10000 Cycles Min.
 - 3.8 Operating condition:Temperature-40°C~+85°C Humidity 80% R.H MAX



Pin No.	MICRO SD
PIN1	DAT2 1P
PIN2	CD/DAT3 2P
PIN3	CMD 3P
PIN4	VDD 4P
PIN5	CLK 5P
PIN6	VSS 6P
PIN7	DAT0 7P
PIN8	DAT1 8P
PIN9	CARD DETECT

Switch card state



ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	10	COPPER ALLOY	
①	Housing	1	HI-TEMP.PLASIC UL 94V-0	BLACK

广东星坤科技股份有限公司

生	日期
ΔX	
ΔX	
ΔX	

MARK	DESCRIPTION	DATE	REVISED	APPROVED	REVISIONS
					UNSPECIFIED TOLERANCES

DSND	DATE	SCALE: N/A	MODEL TYPE:		
DWN	DATE	VIEW:	TF CARD CONN		
CHKD	DATE	UNIT: mm/in	PART NO.:		
APPD	DATE	SIZE: A4	DWG NO.:		
			XKTF-001C		
			WEIGHT	SHEET	REVISION
			1.0g	1/1	A0

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